



FH8815DC

N-Channel Trench Power MOSFET

◆ General Description

The FH8815DC is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

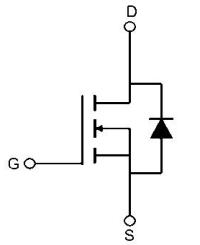
◆ Features

- $R_{DS(ON)} \leq 90 \text{ m}\Omega @ V_{GS}=10\text{V}$
- $R_{DS(ON)} \leq 110 \text{ m}\Omega @ V_{GS}=4.5\text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

◆ Applications

- Power Management
- DC/DC Converter
- Load Switch

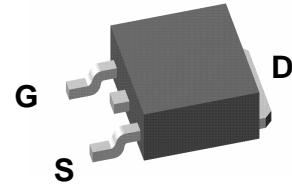
TO-252



Schematic diagram



Marking and pin assignment



TO-252 top view

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		150	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current ^{note5}	$T_C = 25^\circ\text{C}$	18	A
I_D	Continuous Drain Current ^{note5}	$T_C = 100^\circ\text{C}$	12	A
I_{DM}	Pulsed Drain Current ^{note3}		72	A
P_D	Power Dissipation ^{note2}	$T_C = 25^\circ\text{C}$	75	W
I_{AS}	Avalanche Current ^{note3,6}		5.5	A
E_{AS}	Single Pulse Avalanche Energy ^{note3,6}		75	mJ
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.2	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ^{note1,4}		59	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

◆ **Electrical Characteristics** ($T_J=25^\circ\text{C}$, unless otherwise noted)

Static

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}$, $I_D = 250\mu\text{A}$	150	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_D = 250\mu\text{A}$	1.5	-	3.0	V
I_{GSS}	Gate Body Leakage	$V_{\text{DS}} = 0\text{V}$, $V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
$I_{\text{DS}}^{\text{SS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 150\text{V}$, $V_{\text{GS}} = 0\text{V}$	-	-	1	μA
$R_{\text{DS(ON)}}$	Drain-Source On On-Resistance	$V_{\text{GS}} = 10\text{V}$, $I_D = 10\text{A}$	-	75	90	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}$, $I_D = 8\text{A}$	-	84	110	
V_{SD}	Diode Forward Voltage	$I_S = 1\text{A}$, $V_{\text{GS}} = 0\text{V}$	-	0.72	1	V

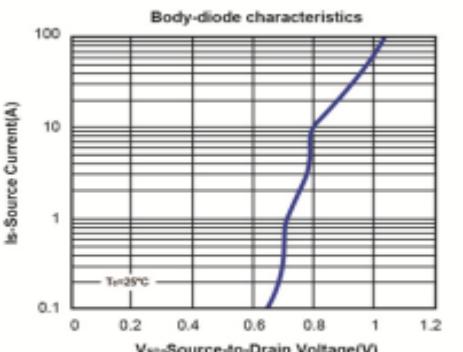
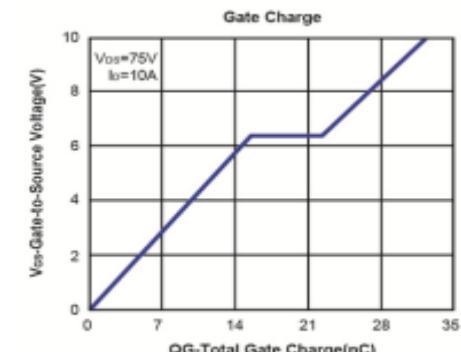
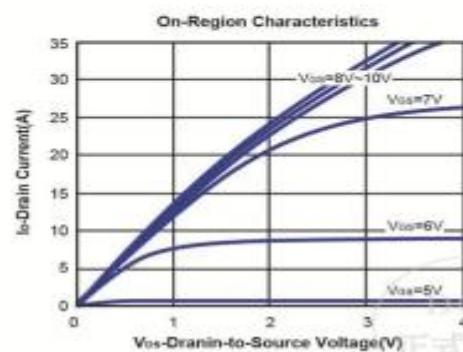
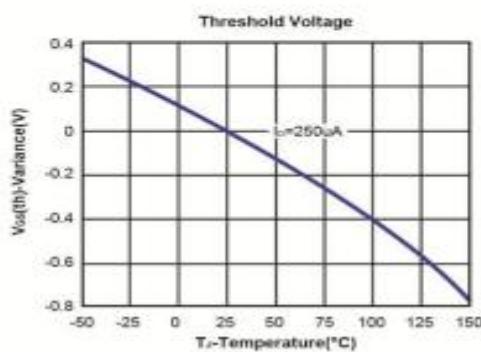
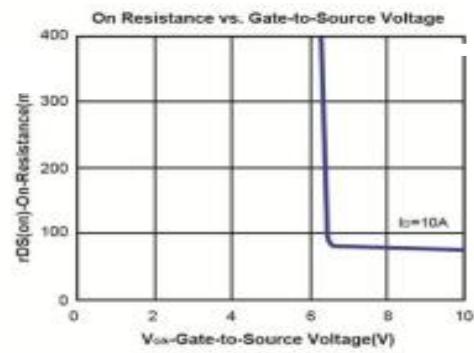
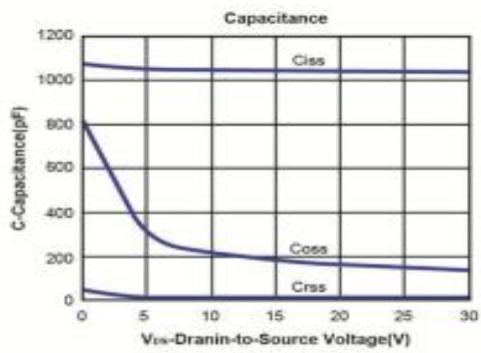
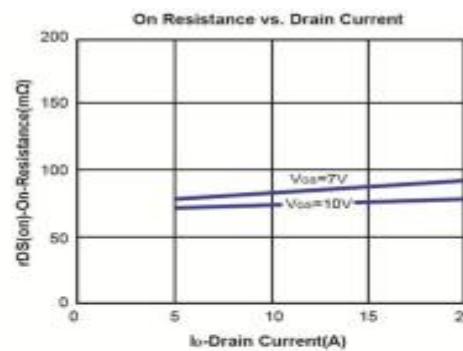
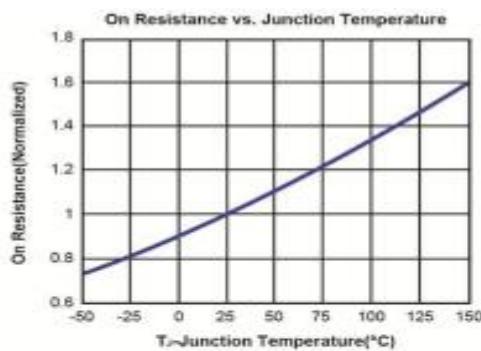
Dynamic

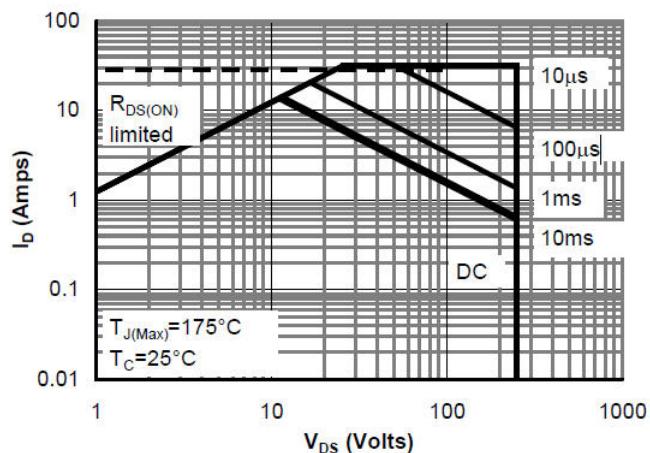
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q_g	Total Gate Charge	$V_{\text{DD}} = 75\text{V}$ $V_{\text{GS}} = 10\text{V}$ $I_D = 10\text{A}$	-	32.3	-	nC
Q_{gs}	Gate-Source Charge		-	15.7	-	
Q_{gd}	Gate-Drain Charge		-	6.62	-	
C_{iss}	Input Capacitance	$V_{\text{DS}} = 30\text{V}$ $V_{\text{GS}} = 0\text{V}$ $f = 1\text{MHz}$	-	1039	-	pF
C_{oss}	Output Capacitance		-	136	-	
C_{rss}	Reverse Transfer Capacitance		-	14	-	
$t_{d(on)}$	Turn-On Delay Time	$V_{\text{DD}} = 75\text{V}$ $V_{\text{GS}} = 10\text{V}$ $R_G = 3\Omega$ $I_D = 1\text{A}$	-	24.9	-	ns
t_r	Turn-On Rise Time		-	6.02	-	
$t_{d(off)}$	Turn-Off Delay Time		-	49.9	-	
t_f	Turn-Off Fall Time		-	20	-	

Notes:

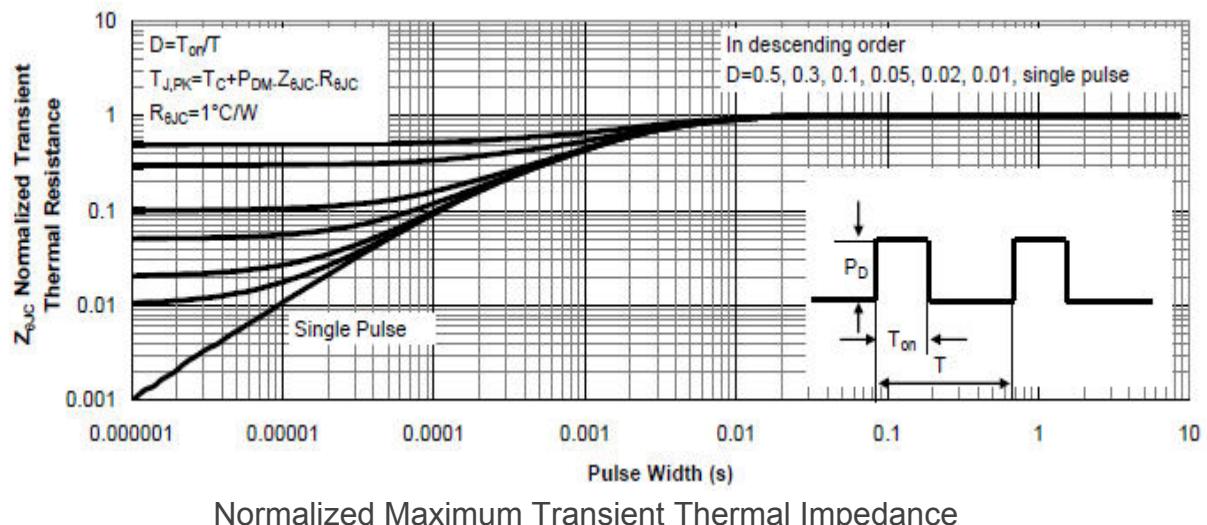
- The value of $R_{\theta_{JC}}$ is measured in a still air environment with $TA = 25^\circ\text{C}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.
- The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- Single pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
- The $R_{\theta_{JA}}$ is the sum of the thermal impedance from junction to case $R_{\theta_{JC}}$ and case to ambient.
- The maximum current rating is package limited.
- The EAS data shows Max. rating. The test condition is $V_{\text{DS}}=75\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=5\text{mH}$

◆ Typical Characteristics ($T_J = 25^\circ\text{C}$ Noted)



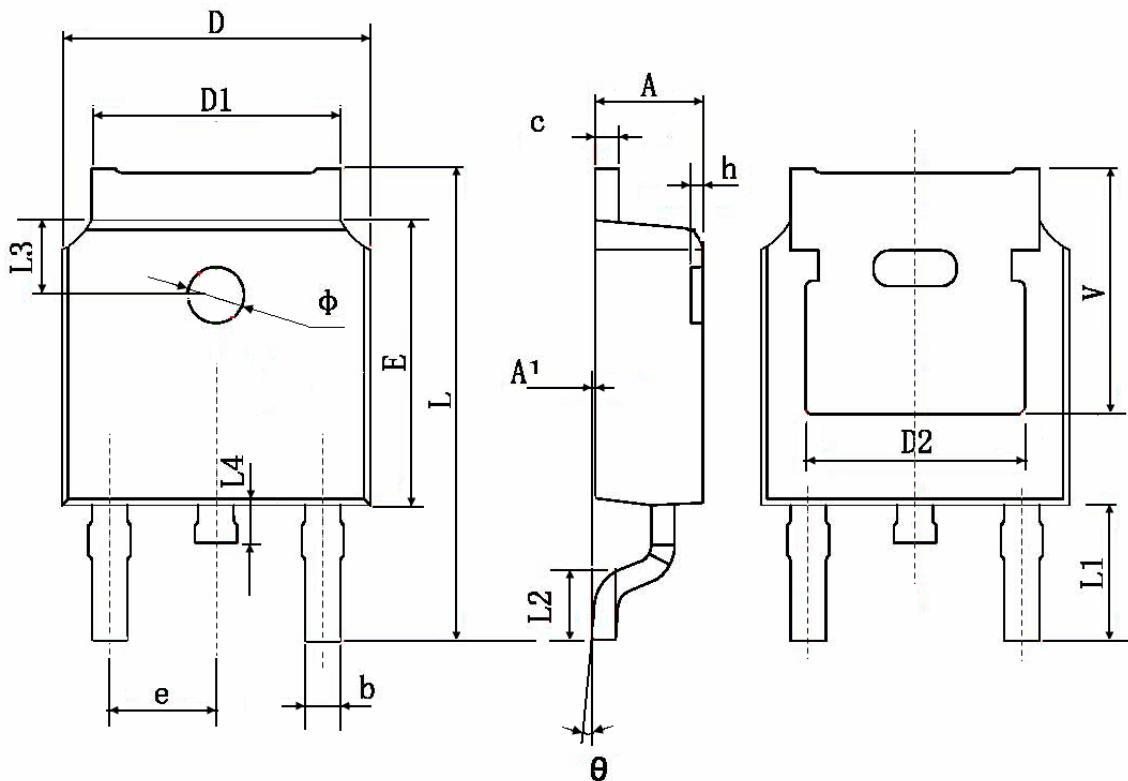


**Maximum Forward Biased Safe
Operating Area**



Normalized Maximum Transient Thermal Impedance

Package Information : TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	